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	Application No.	Applicant(s)	
	pp. ea.o. no.		
Notice of Allowability	10/607,400	DOWNES ET AL.	
Notice of Anonability	Examiner	Art Unit	
	Jonathan Johnson	1725	
The MAILING DATE of this communication appearance All claims being allowable, PROSECUTION ON THE MERITS IS herewith (or previously mailed), a Notice of Allowance (PTOL-85) NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT RI of the Office or upon petition by the applicant. See 37 CFR 1.313	(OR REMAINS) CLOSED in this apport or other appropriate communication GHTS. This application is subject to	plication. If not included will be mailed in due course. THIS	
1. $\square$ This communication is responsive to <u>7-24-06</u> .			
2.  The allowed claim(s) is/are <u>1-10,40-50</u> .			
<ul> <li>3. Acknowledgment is made of a claim for foreign priority una a) All b) Some* c) None of the:</li> <li>1. Certified copies of the priority documents have 2. Certified copies of the priority documents have 3. Copies of the certified copies of the priority documents</li> </ul>	been received. been received in Application No		
International Bureau (PCT Rule 17.2(a)).			
* Certified copies not received:			
Applicant has THREE MONTHS FROM THE "MAILING DATE" of this communication to file a reply complying with the requirements noted below. Failure to timely comply will result in ABANDONMENT of this application.  THIS THREE-MONTH PERIOD IS NOT EXTENDABLE.			
4. A SUBSTITUTE OATH OR DECLARATION must be submitted. Note the attached EXAMINER'S AMENDMENT or NOTICE OF INFORMAL PATENT APPLICATION (PTO-152) which gives reason(s) why the oath or declaration is deficient.			
5. CORRECTED DRAWINGS (as "replacement sheets") must be submitted.			
(a) ☐ including changes required by the Notice of Draftsperson's Patent Drawing Review ( PTO-948) attached			
1)  hereto or 2)  to Paper No./Mail Date			
(b) ☐ including changes required by the attached Examiner's Amendment / Comment or in the Office action of Paper No./Mail Date			
Identifying indicia such as the application number (see 37 CFR 1.84(c)) should be written on the drawings in the front (not the back) of each sheet. Replacement sheet(s) should be labeled as such in the header according to 37 CFR 1.121(d).			
6. DEPOSIT OF and/or INFORMATION about the deposit of BIOLOGICAL MATERIAL must be submitted. Note the attached Examiner's comment regarding REQUIREMENT FOR THE DEPOSIT OF BIOLOGICAL MATERIAL.			
Attachment(s)			
1. Notice of References Cited (PTO-892)	5. Notice of Informal P	atent Application	
2. Notice of Draftperson's Patent Drawing Review (PTO-948)	· /	6. Interview Summary (PTO-413) Paper No./Mail Date 2000 6918 7. Examiner's Amendment/Comment	
3. Information Disclosure Statements (PTO/SB/08), Paper No./Mail Date  4. Examinada Comment Bosselina Bassilian Bass			
<ol> <li>Examiner's Comment Regarding Requirement for Deposit of Biological Material</li> </ol>	<ul><li>8.</li></ul>	ent of Reasons for Allowance	
	J. Џ Ошег		

## **EXAMINER'S AMENDMENT**

An examiner's amendment to the record appears below. Should the changes and/or additions be unacceptable to applicant, an amendment may be filed as provided by 37 CFR 1.312. To ensure consideration of such an amendment, it MUST be submitted no later than the payment of the issue fee.

Authorization for this examiner's amendment was given in a telephone interview with Jeffrey Duquette on 9-18-06.

The application has been amended as follows:

Cancel claim 39.

In claim 40, Line 1, change "39" to --1--.

In claim 1, line 19, replace "stencil." with --stencil; and

wherein the circuit board fabrication stage, when fabricating the circuit board having the set of circuit board pads, is configured to glue, heat, and press together layers of non-conductive and conductive material into a substantially rigid planar structure having signal planes, traces, and contacts to form a network of electrical pathways between multiple integrated circuit device packages and a support surafce to support the multiple integrated circuit device packages; and

wherein the circuit board pads are Surface Mount Technology (SMT) pads which are adapated to soldering to integrated circuit packages having SMT package contacts; and wherein

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the solder fusing stage, when activating the flux and melting the solder to form the set of substantially flat solder coatings which is fused to the set of circuit board pads, is configure to:

apply high heat to form as the set of substantially flat solder coatings, a set of solderable structures having (i) intermetallic bonds with the set of SMT pads, and (ii) external surfaces with high solder affinity in order to solder to the SMT package contacts of the integrated circuit packages during an SMT circuit board assembly process.--

In claim 41, line 21, replace "stencil." with --stencil; and

wherein the circuit board fabrication stage, when fabricating the circuit board having the set of circuit board pads, is configured to glue, heat, and press together layers of non-conductive and conductive material into a substantially rigid planar structure having signal planes, traces, and contacts to form a network of electrical pathways between multiple integrated circuit device packages and a support surafce to support the multiple integrated circuit device packages.--

## Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Jonathan Johnson whose telephone number is 571-272-1177. The examiner can normally be reached on M-Th 7:30 AM-5:30 PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Pat Ryan can be reached on 571-272-1292. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

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Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

Jonathan Johnson Primary Examiner Art Unit 1725